

Preface

CMP (chemical mechanical planarization), as one of the most important processes in the semiconductor manufacturing, has been developed and improved continuously year after year. It has built a certain position in related industries, and is expanding in its applied area. From the user's point of view, technical demand is becoming higher and higher, and additional applications beyond the semiconductor area are increasing.

ICPT (International Conference on Planarization / CMP Technology), is a magnificent opportunity to have discussions on CMP technologies, including FEOL and BEOL CMP, Fundamentals of CMP, Polishing Processes, Consumables, Equipment, 3D / TSV, Metrology, Cleaning, Defect Control, Process Control, etc.

The conference provides a place where every relevant researcher and engineer can get together to discuss openly and exchange information widely.

Gerfried Zwicker and Patrick Ong
Conference Chairs

Ronald Schnabel
Conference Organizer